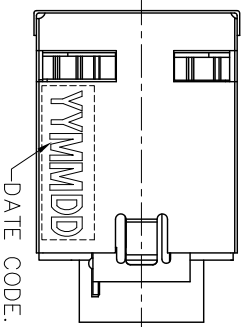
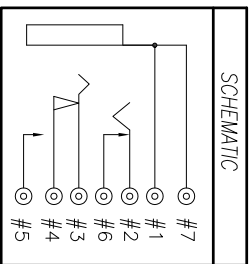
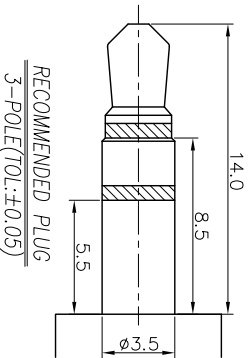


RECOMMENDED PCB LAYOUT (TOP VIEW)  
(TOLERANCE: ±0.05)



**SPECIFICATIONS:**

1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
2. CONTACT RESISTANCE: 30mΩ MAX.
3. INSULATION VOLTAGE WITHSTAND:  
500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
6. INSERTION FORCE :0.4 - 3kgf
7. WITHDRAWAL FORCE: 0.3 - 2kgf.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
10. PACKAGING : TAPE & REEL.
11. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
12. GREEN PRODUCT IDENTIFICATION MARK ON JACK:
13. GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
14. FOR LEAD-FREE PROCESS.

REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A	PDR:	T080509-2A	BRUCE	2008.05.29
B	ECN:	S090827	BRUCE	2010.01.06
C	ECN:	S110128	Swing	2011.01.21
D	ECN NO:	S121215	Cerry	2013.04.17

H	SHIELDING	1	SUS 0.12T	NI 60U" MIN.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	120U" Sn ON SOLDER TAIL
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA ALL OVER 50U" NI.
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD TEST ON CONTACT AREA ALL OVER 50U" NI.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag20U" Min.
B	EARTH	1	COPPER ALLOY 0.3t	ALL OVER 50U" NI.
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK
NO DESCRIPTION		QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS:		ANGLES:		
X	:±0.5	X	:±2°	
X,X	:±0.3	X,X	:±1°	
X,XX	:±0.2			
TITLE		3.5φ PHONE JACK		
DWN	Cerry	PART NO.	2SJ-S351-027	
CHKD	lom	SCALE:	4:1	
APVD	Max	SIZE:	A3	
		SHEET:	1 OF 1	
		REV:	D	
<b>CUSTOMER COPY</b>				

Singatron Enterprise Co., Ltd.  
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